

Semico Fab Database Update Summary Second Half 2016

December 2016

MA107-16

©Copyright Semico Research Corp. 2016. All rights reserved.

Reproduction in whole or part is prohibited without permission of Semico Research

The contents of this report represent the interpretation and analysis of statistics and information that is generally available to the public or released by responsible agencies or individuals, but is not guaranteed as to its accuracy or completeness.

Table of Contents

Table of Contents	iii
Fab Database Updates.....	1
Memory	1
Micron/Inotera	1
Samsung.....	1
SK Hynix.....	2
Toshiba/WD.....	2
Winbond	2
XMC/YRST.....	2
Foundries	3
Samsung.....	3
SMIC	3
Toshiba.....	3
TSMC.....	3
UMC	3
X-FAB	4
Other.....	4
Analog Devices / Linear Technology.....	4
Fairchild/ON Semiconductor.....	4
Infineon	4
Qualcomm/NXP Semiconductors	4
Renesas/Intersil	5
TDK.....	5

Below are the column headings included in the Excel workbook accompanying this Word document. There are 949 rows in the workbook:

Status
 Company
 FabName
 Region
 Country
 City
 State/ Region
 Special Substrate
 University
 Development
 IDM
 Foundry
 Process Type
 Products
 Logic
 ASSPs
 ASICs
 Analog
 Discretes
 Passives
 Opto
 DRAM
 Mobile RAM
 SRAM
 NAND
 NOR
 Other NV Memory
 MEMS
 Image Sensors
 Oth Sensors
 LED
 LED Drivers
 LCD Drivers
 Other
 Bipolar
 Current Process Tech (nm)
 FinFET
 Wafer Size (mm)

450mm capable
 Full Capacity (w/mo)
 Full Capacity (8-in Equiv/ mo)
 Construction Start
 Initial Prod Yr
 Vol Prod Yr
 Yr Closed or Closing
 Empl
 Total Capex (millions)
 Site Size
 Total Fab Size (K sq. m)
 Cleanroom Size (K sq. m)